



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20180417000
Datasheet for AM26LV31
Information Only**

Date: May 14, 2018
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is a notice of change to a product data sheet for a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

**Data Sheet Change Notification
Attachments**

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
AM26LV31CD	null
AM26LV31CNSR	null
AM26LV31CDRG4	null
AM26LV31IDR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20180417000	PCN Date:	May 14, 2018
Title:	Datasheet for AM26LV31 <input type="checkbox"/>		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Aug 14, 2018		
Change Type:			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site	
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material	
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site	
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials	
		<input type="checkbox"/> Wafer Fab Process	

Notification Details

Description of Change:

The product datasheet(s) is being updated as summarized below.
The following change history provides further details.

The datasheet number will be changing.



AM26LV31

SLLS201H – MAY 1995 – REVISED APRIL 2018

Changes from Revision G (May 2005) to Revision H

Page

- Added Device Information table, ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section 1
- Changed the t_{PLH} and t_{PHL} MAX value From: 12 ns To: 20 ns in the Switching Characteristics 5
- Changed the $t_{sk(p)}$ and $t_{sk(o)}$ MAX value From: 1.5 ns To: 3 ns in the Switching Characteristics 5

The datasheet number will be changing.

Device Family	Change From:	Change To:
AM26LV31	SLLS201G	SLLS201H

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/AM26LV31>

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

Electrical specification performance changes as indicated above.

Changes to product identification resulting from this PCN:

None.

Product Affected:

AM26LV31CD	AM26LV31CDR	AM26LV31CNSR	AM26LV31IDR
AM26LV31CDE4	AM26LV31CDRE4	AM26LV31ID	AM26LV31INSR
AM26LV31CDG4	AM26LV31CDRG4	AM26LV31IDG4	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com

Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com